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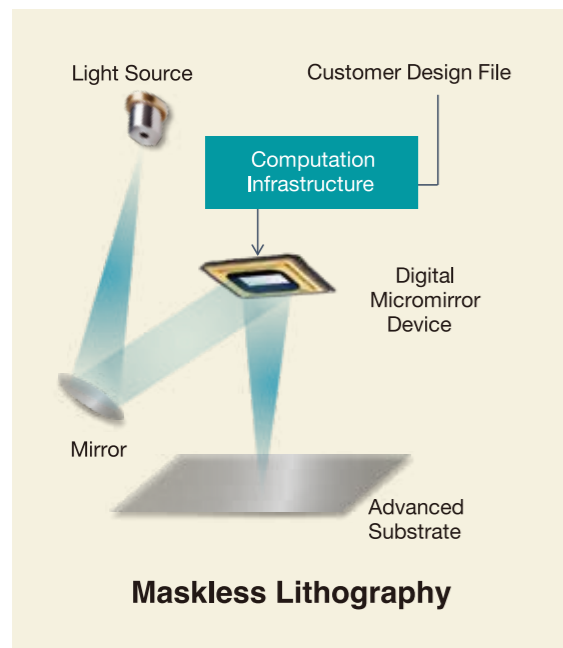
DLT-Series

Digital Lithography Technology

Digital Lithography Technology for Advanced packaging

DLT-Series

DIGITAL LITHOGRAPHY TECHNOLOGY BY APPLIED MATERIALS®

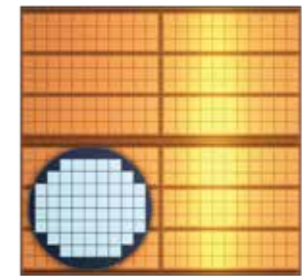
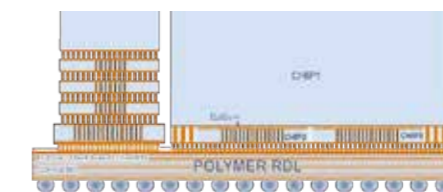
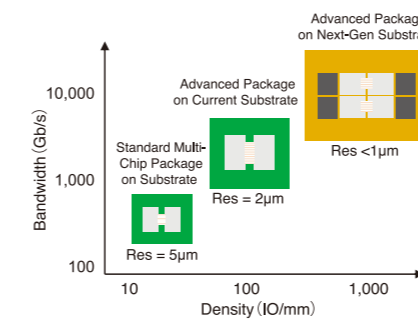


Specification	DLT-W Series WLP	DLT-P Series PLP
Resolution L/S	1µm, 2µm, 5µm Configurations	
Overlay	Down to ±0,35µm	
Substrate Size	300mm wafer, glass	510mm x 515mm panel CCL, glass

AI Drives Advanced Package Innovation



Packaging Lithography Roadmap

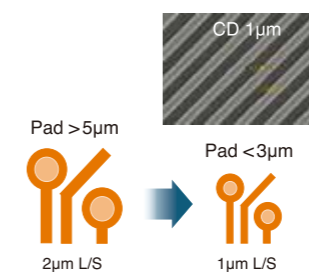


- AI drives larger data center processors
- Beyond reticle limit
- HI enables scaling
- Larger packages with more functionality
- Advanced packages require substrate innovation
- New materials (glass) and sizes (panel)

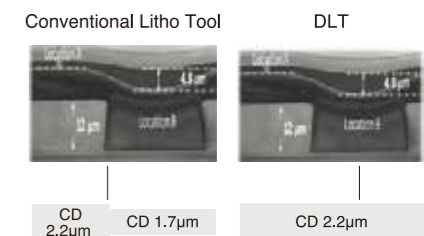
Benefits for Customers



- High resolution 1µm to shrink pad area for I/O density
- High overlay 0.35µm to yield on reduced pad area
- Dry and liquid film resists

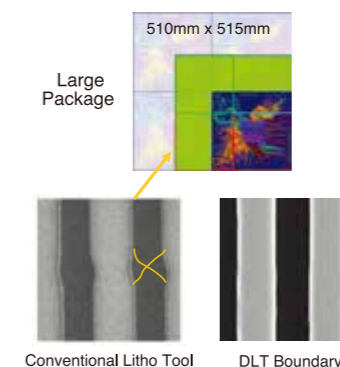


- Local field-of-view focus
- On-the-fly auto focus for topographic variation
- Better LER on rough surface



Unlimited Field + Seamless Stitching

- No field size limit
- No yield loss on mask stitching
- Ideal for large packages



Design Cycle Time

- Mask cost savings
- Cycle time < 1 day
- Design IP security
- Fast time-to-market

